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[54] METHOD OF UNIFORMLY COATING A SUBSTRATE

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[58] Field of Search 118/52; 427/240, 427/335; 437/231

References Cited [56]

U.S. PATENT DOCUMENTS

4,068,019	1/1978	Boeckl .
4,113,492	9/1978	Sato et al
4,132,357	1/1979	Blackinton .
4,267,212	5/1981	Sakawaki .
4,347,302	8/1982	Gotman.
4,393,807	7/1983	Fujimura et al
4,438,159	3/1984	Weber .
4,510,176	4/1985	Cuthbert et al
4,514,440	4/1985	Justice et al
4,518,678	5/1985	Allen.
4,600,597	7/1986	White et al
4,732,785	3/1988	Brewer .
4,741,926	5/1988	White et al
4,800,836	1/1989	Yamamoto et al
4,822,639	4/1989	Fuji et al
4,886,012	12/1989	Ikeno et al
4,932,353	6/1990	Kawata et al
4,946,710	8/1990	Miller et al
4,963,390	10/1990	Lipeles et al

5,013,586	5/1991	Cavazza.
5,066,616	11/1991	Gordon .
5 094 884	3/1992	Hillman et al

(List continued on next page.)

FOREIGN PATENT DOCUMENTS

	279033	5/1990	Germany
	46-10790	3/1971	Japan .
	46-42658	12/1971	Japan .
	57-45369	3/1982	Japan .
4	57-130432	8/1982	Japan .
	60-10248	1/1985	Japan .
-	50-226125	11/1985	Japan .
	61-29125	2/1986	Japan .
	62-225269	10/1987	Japan .
- (63-119531	5/1988	Japan .
	1-27667	1/1989	Japan .
	1-238017	9/1989	Japan .
	2-98126	4/1990	Japan .
	2-119226	5/1990	Japan .
	3-41715	2/1991	Japan .
	4-62915	2/1992	Japan .
	4-9823	3/1992	Japan .
	4-104158	4/1992	Japan .
	5-166712	7/1993	Japan .

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A method of and an apparatus for coating a substrate with a polymer solution to produce a film of uniform thickness, includes mounting the substrate inside an enclosed housing and passing a control gas, which may be a solvent vaporbearing gas into the housing through an inlet. The polymer solution is deposited onto the surface of the substrate in the housing and the substrate is then spun. The control gas and any solvent vapour and particulate contaminants suspended in the control gas are exhausted from the housing through an outlet and the solvent vapor concentration is controlled by controlling the temperature of the housing and the solvent from which the solvent vapor-bearing gas is produced. Instead the concentration can be controlled by mixing gases having different solvent concentrations. The humidity of the gas may also be controlled.

ABSTRACT

4 Claims, 2 Drawing Sheets

